# **ISOLA LAMINATE SYSTEMS**

### **G200**

#### **BT/Epoxy Laminate and Prepreg**

Isola Laminate Systems' G200 is a fully proven laminate and prepreg system designed to meet today's high reliability printed wiring board requirements. Blending bismaleimide/triazine and epoxy resin provides G200 with enhanced thermal, mechanical and electrical performance over most epoxy materials. G200 possesses performance characteristics that make it an excellent selection for large panel size, high layer count printed wiring boards.

#### Performance and Processing Advantages

#### • High Tg - 185°C (DSC)

Superior performance through multiple thermal excursions Superior chemical and thermal resistance

- Lower CTE from Ambient to 288°C
- Excellent Electrical Insulation in High Humidity and High Temperatures (CAF Resistance)
- Very Consistent Dimensional Stability Excellent layer-to-layer registration

#### **Purchasing Information**

- Industry Approvals IPC 4101/30 UL Recognized - UL File Number E41625
- Standard Availability
   Thicknesses: 0.002" [.05 mm] to 0.125" [3.2 mm]
   Available in sheet or panel form
   Copper Foil Cladding: <sup>1</sup>/<sub>8</sub> to 3 oz.
   Options HTE, Double-Treat

  Prepregs: Available in roll or panel form
  Glass Styles 106, 1080, 2313, 2116, 1652, 7628

## Product and Solutions Offering

Isola Laminate Systems' broad range of laminate, prepreg and foil products and solutions includes:

• PWB Substrates FR-4s Composites • Advanced PWB Substrates BT/Epoxy G200 Polyimide Specialty Prepregs

- HDI Materials
- Signal Integrity Substrates
- Packaging Substrates

# isola

#### Ordering Information

Contact your local sales representative or the Inside Sales Department in La Crosse, WI.

Phone: 1-800-845-2904 or 608-784-6070 Fax: 1-800-344-1825 or 608-791-2428

Isola Laminate Systems Corp. 230 North Front Street La Crosse, WI 54601

For further information visit *www.isolalaminatesystems.com* 

# G200 Typical Laminate Properties, 0.008" [0.20mm]

PROPERTY Thickness Construction Retained Resin	UNITS inches mm — %	<b>IPC 4101</b> <0.030 [<0.78] 	G200 VALUE 0.008 [0.20] 2313/2116 48	CONDITIONING   
Thermal Tg, range (DSC) CTE - x-axis y-axis z-axis Solder Float, 288°C	°C ppm/°C ppm/°C ppm/°C seconds	170-220 	185 15 15 140 >1200	E-2/105 Ambient to Tg Ambient to Tg Ambient to 288°C E-2/105
Electrical Permittivity (Dk), max. @ I MHz (2 Fluid Cell) 500 MHz (HP 4291) I GHz (HP 4291) Loss Tangent (DF), max. @ I MHz 500 MHz (HP 4291) I GHz (HP 4291) Surface Resistivity, min. Volume Resistivity, min. Electric Strength, min. Arc Resistance, min.	   megohms megohms-cm megohms-cm volts/mil [volts/mil [volts/mm] seconds	4.8 	4.1 3.9 3.9 0.013 0.009 0.009 1×10 <sup>8</sup> 1×10 <sup>5</sup> 1×10 <sup>7</sup> 1×10 <sup>7</sup> 1×10 <sup>7</sup> 1×10 <sup>7</sup> 1×10 <sup>7</sup>	C-24/23/50 C-24/23/50 C-24/23/50 C-24/23/50 C-24/23/50 C-24/23/50 C-96/35/90 E-24/125 C-96/35/90 E-24/125 D-48/50 D-48/50 D-48/50
Physical Peel Strength, min 1 oz. Flammability Moisture Absorption, max.	lb/in [Kg/M] Ib/in [Kg/M] Ib/in [Kg/M] — %	 5.0 [90] 1.9 [35] V-0 ≤0.80	7.0 [125] 7.0 [125] 5.0 [90] V-0 0.14*	Condition A Condition A After Thermal Stress After Thermal Stress E-1/150 E-1/150 UL94 D-24/23

\*Material Thickness Tested - 0.028"

"The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold."